

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. – 10. (cancelled)

11. (currently amended) An apparatus comprising:

an electronic component body; and

one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg and a second leg, the first leg and the second leg defining a first acute angle therebetween, the second leg comprising a first portion defining the first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, and a fourth portion defining a second obtuse angle with the third portion,

wherein the third portion is substantially parallel to the first leg,

wherein a length of the third portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted,

wherein a vertex of the first obtuse angle is to abut the substrate, and

wherein the substrate is to be disposed between the vertex and the electronic component body.

12. – 14. (cancelled)

15. (currently amended) A method comprising:

bending an electronic component body lead to form a first leg and a second leg, the first leg and the second leg defining a first acute angle therebetween; and

bending the second leg to form a first portion defining the first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, and a fourth portion defining a second obtuse angle with the third portion,

wherein the third portion is substantially parallel to the first leg,

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the third portion that is substantially parallel to the first leg is substantially equal to a thickness of a substrate to which the electronic component body is to be mounted.

16. – 18. (cancelled)

19. (original) A method according to Claim 15, further comprising:
electrically coupling the lead to an electronic component body.

20. (original) A method according to Claim 15, wherein the lead is attached to an electronic component body.

21. (currently amended) A method comprising:

placing a lead of an electronic component body into an opening of a substrate, wherein the lead comprises a first leg and a second leg defining a first acute angle therebetween, the second leg comprising a first portion defining the first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first

obtuse angle with the second portion, and a fourth portion defining a second obtuse angle with the third portion,

wherein the third portion is substantially parallel to the first leg,

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the third portion that is substantially parallel to the first leg is substantially equal to a thickness of the substrate.

22. – 24. (cancelled)

25. (original) A method according to Claim 21, further comprising:

electrically coupling the lead to the substrate.

26. (currently amended) An expansion card comprising:

a circuit board;

a connector coupled to the circuit board, the connector to connect to a motherboard; and

an electronic component body coupled to the circuit board, the electronic component body comprising one or more leads coupled to and extending from the electronic component body,

wherein a first lead of the one or more leads comprises a first leg, and a second leg, the first leg and the second leg defining a first acute angle therebetween, the second leg comprising a first portion defining the first acute angle with the first leg, a second portion defining a second acute angle with the first portion, and a third portion defining a first obtuse angle with the second portion, and a fourth portion defining a second obtuse angle with the third portion,

wherein the third portion is substantially parallel to the first leg,

wherein a vertex of the first obtuse angle is to abut the substrate,

wherein the substrate is to be disposed between the vertex and the electronic component body, and

wherein a length of the third portion that is substantially parallel to the first leg is substantially equal to a thickness of the circuit board.

27. – 29. (cancelled)

30. (new) An apparatus according to claim 11, wherein the first lead is tin-coated.

31. (new) A method according to Claim 15, wherein the electronic component body lead is tin-coated.

32. (new) A method according to Claim 21, wherein the lead of the electronic component body is tin-coated.

33. (new) An expansion card according to claim 26, wherein the first lead is tin-coated.